

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/09/2022

Details for "TLV70025DCKT"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLV70025DCKT	NIPDAU	Level-1-260C-UNLIM	Ext-Mfg	DCK 5	1.25x2x0.9	6.3

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Precious Metals	Gold	7440-57-5	0.029857	100	1000000	0.475288	4753
Sub-Total			0.029857	100	1000000	0.475288	4753
Die Attach Adhesive							
Other Inorganic Materials	Aluminum Oxide	1344-28-1	0.011773	29.998726	299987	0.187412	1874
Other Inorganic Materials	Silica	7631-86-9	0.001766	4.499936	44999	0.028113	281
Other Organic Materials	Chlorine	7782-50-5	0.000014	0.035673	357	0.000223	2
Thermoplastics	Epoxy	85954-11-6	0.025692	65.465664	654657	0.408986	4090
Sub-Total			0.039245	100	1000000	0.624734	6247
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	2.596709	97.437486	974375	41.336521	413365
Copper and Its Alloys	Iron	7439-89-6	0.062628	2.350019	23500	0.996963	9970
Copper and Its Alloys	Phosphorus	7723-14-0	0.002199	0.082514	825	0.035005	350
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.000133	0.004991	50	0.002117	21
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.003331	0.124991	1250	0.053026	530
Sub-Total			2.665	100	1000000	42.423633	424236
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.110339	95.119828	951198	1.756466	17565
Precious Metals	Gold	7440-57-5	0.000905	0.780172	7802	0.014407	144
Precious Metals	Palladium	7440-05-3	0.004756	4.1	41000	0.07571	757
Sub-Total			0.116	100	1000000	1.846582	18466
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	2.977126	93.249983	932500	47.392308	473923
Other Plastics and Rubber	Carbon Black	1333-86-4	0.007982	0.250013	2500	0.127064	1271
Thermoplastics	Epoxy	85954-11-6	0.207521	6.500004	65000	3.303488	33035
Sub-Total			3.192629	100	1000000	50.822859	508229
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.239145	100	1000000	3.806904	38069
Sub-Total			0.239145	100	1000000	3.806904	38069
Total			6.281876			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/eoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.